



- NOTES:
1. GOLD PLATE 100μ INCHES MIN. OVER 70μ INCHES MIN. NICKEL.
  2. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. (SEAL RING ISOLATED)
  3. LEAD RESISTANCE 0.45 OHMS MAX.

**OPEN-TOOLED**

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SDG-012

NTK TECHNICAL CERAMIC DIVISION  
MAY 17 1986  
NGK SPARK PLUG CO., LTD.

UNLESS OTHERWISE SPECIFIED TOLERANCES	DRAWN H.Kondo OCT-8-'82	NGK SPARK PLUG CO., LTD NAGOYA, JAPAN.	
	CHECKED	NTK TECHNICAL CERAMIC DIVISION	
±1% N.L.T. ±0.05	APPROVED <i>Y. Coi</i>	TITLE 20LEAD FLAT PACKAGE	
MATERIAL CERAMIC: 91% BLACK ALUMINA	UNIT INCH	DWG NO	ISSUE
LEAD: KOVER	SCALE x 5	IFK20F1-292A	